

# Call for Abstracts (due February 28, 2020)



## ASME 2020 INTERPACK®

International Technical Conference and Exhibition on Packaging and Integration of Electronic and Photonic Microsystems

**Date: Oct. 27-29, 2020, Location: Hilton Anaheim, Anaheim, CA**

<http://event.asme.org/interpack>

InterPACK is the premier international conference for exchange of state-of-the-art knowledge in research, development, manufacturing, and applications of electronics and photonics packaging and heterogeneous integration. It is the flagship conference of the ASME Electronic and Photonic Packaging Division (EPPD). The international nature of the meeting has been highly beneficial in promoting global interactions between Industry and Academia. In addition to paper presentations and exhibits, InterPACK 2020 will include panel discussions, workshops, tutorials, keynotes and technology talks by prominent speakers, and a Joint Industry, National Lab, Academia poster session. **Abstracts (<400 words) for original papers are solicited in the general track areas of:**

### Heterogeneous Integration: Micro-Systems with Diverse Functionality:

Advanced Packaging, Die Stacking, Multichip Modules, Interconnect Technology, Substrate Technology, Through-Silicon Vias (TSV), Wafer Level Packaging (Fan-in, Fan-out), Panel Level Packaging, System in Package (SiP), Microsystems Integration, Integrated Photonics, RF Packaging, Advanced Materials and Processes, Chip Package Interaction, Modeling, Characterization and Reliability for Integrated Devices, Electronic Materials, Underfills, Molding Compounds, Substrates, Thermal Materials, Dielectrics.

### Servers of the Future, and Edge to Cloud:

Data Centers & Energy Efficient Electronic Systems, Cloud Computing Hardware, Edge to Cloud Systems, Rack Level Cooling, Thermal Interface Materials & Thermal Underfills, Fans & Pumps, Thermosyphons & Refrigeration, Exaflop Computing Systems, Memory, Connectors, Advanced Substrates, Novel Cooling Techniques, Heat Exchangers, Device to System Level Packaging.

### Flexible and Wearable Electronics:

Wearables, Internet of things, Asset Monitoring, Implantable Medical Devices, Microfluidics, Interconnects, Substrate Materials, Printed Electronics, Thin Die Handling, Non-Contact Processes. Sensors & Actuators, RF Resonators, Fabrication, Integration, Hermetic Packaging, & Reliability, Biosystems & Biomedicine, and Industry Perspectives. Reliability of devices, Interconnects, Solder Joint Reliability, Materials Interactions, Chemical, Biological, and Physical Implications, System Level Reliability Issues, Materials

characterization, Reliability Modelling and Simulation, Reliability Test Methods, Prognostics and Health Monitoring.

### Photonics and Optics:

Photonics packaging, Optical integration, Thermal and mechanical challenges for optical photonics integration, LED: thermal, mechanical, reliability and its integration.

### Power Electronics:

Wide Bandgap Semiconductor Packaging, Power Electronics, Harsh Environment Sensors, High Temperature Electronics for Oil & Gas and Geothermal Energy, Novel Interconnects, Graphene & CNT Materials and Devices, Heat Transport, Fracture, Fatigue, and Delamination of Interfaces and Interconnects, Thermomechanical Stress and Device Reliability.

### Multiscale Energy Transport, Conversion, and Storage:

Energy Harvesting, Energy Storage, Thermoelectrics, Photovoltaics, energy transport at multiscale, Nanoscale Heat Transport.

### Autonomous, Hybrid, and Electric Vehicles:

Electronics for Vehicle Electrification, High Temperature Sensors, RADAR, LIDAR, Advanced Driver Assistance System (ADAS) Electronics, MEMS packaging, Control Systems, Electronic Materials, Nanosatellites, Unmanned Aerial Vehicle (UAV) Electronics, Hybrid Packaging, Prognostic Health Monitoring, Vehicle Charging, Wireless Power Transfer, Energy Conversion, Electric Drive Technologies (e.g. Electric Machines), Motor Control Sensing, and Battery Management.

### KEYNOTE TALKS

- Dr Suresh Ramalingam, Fellow, Xilinx, "Advanced Electronic Packaging and Integration"
- Ritesh Jain, VP, Intel DCG, "Challenges and Opportunities for Future Servers and Data Center"
- Scott Miller: CTO, NextFlex, "Flexible Electronics"

### PUBLICATION SCHEDULE

Abstract Submission	Feb 28, 2020
Draft Paper Submission	April 16, 2020
Draft Paper Decisions	May 28, 2020

Copyright Submission	Jul 13, 2020
Final Paper Submission	Jul 13, 2020
Posters/Presentation Only Abstracts	Jul 13, 2020



### Direct general inquiries to:

General Chair: Jin Yang (jin1.yang@intel.com)  
General Vice Chair: Ankur Jain (jaina@uta.edu)  
Program Chair: Baris Dogruoz (bdogruoz@cisco.com)  
Program Co-Chair: Przemek Gromala (Przemyslaw.Jakub.Gromala@de.bosch.com)  
Program Co-Chair: Lauren Boteler (lauren.m.boteler.civ@mail.mil)

